

# Polishing Slurry for Oxide layer CMP

## ILD™

### Fumed Silica Slurry for Oxide layer Polishing

#### ILD™ Series

#### ▣ Advantages

- Particle stability (Lower scratch)
- High mechanical polishing ability
- Dilutable
- High purity
- KOH/NH3 base



#### ▣ Physical Property

Slurry	ILD3013	ILD3225
Chemical	NH3	KOH
Abrasive (wt%)	13.7	25.7
pH	10.5	11.0
Particle size (nm)	85	85
Viscosity (cP)	1.8	3.7
Specific Gravity	1.08	1.17
Dilution	Ready to use	1:1 dilution

※ ILD™ is the trademark of NITTA DuPont Incorporated.

※ The values such as a physical properties indicated, show the standard value. The product specifications are not guaranteed.